

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/09/2022

Details for "TLV9362IPWR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV9362IPWR	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	PW 8	3x4.4x1.0	39.3

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.02395	97.532171	975322	0.061007	610
Not Categorized	Proprietary Materials		0.000003	0.012217	122	0.000008	0
Precious Metals	Gold	7440-57-5	0.000013	0.05294	529	0.000033	0
Precious Metals	Palladium	7440-05-3	0.000589	2.398599	23986	0.0015	15
Precious Metals	Silver	7440-22-4	0.000001	0.004072	41	0.000003	0
Sub-Total			0.024556	100	1000000	0.062551	626
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.152061	80.000105	800001	0.387341	3873
Thermoplastics	Epoxy	85954-11-6	0.038015	19.999895	199999	0.096835	968
Sub-Total			0.190076	100	1000000	0.484176	4842
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	15.79824	97.461523	974615	40.242471	402425
Copper and Its Alloys	Iron	7439-89-6	0.3726	2.298621	22986	0.949115	9491
Copper and Its Alloys	Phosphorus	7723-14-0	0.00486	0.029982	300	0.01238	124
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00486	0.029982	300	0.01238	124
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.00486	0.029982	300	0.01238	124
Zinc and Its Alloys	Zinc	7440-66-6	0.0243	0.14991	1499	0.061899	619
Sub-Total			16.20972	100	1000000	41.290624	412906
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.722912	95.12	951200	1.841456	18415
Precious Metals	Gold	7440-57-5	0.005928	0.78	7800	0.0151	151
Precious Metals	Palladium	7440-05-3	0.03116	4.1	41000	0.079373	794
Sub-Total			0.76	100	1000000	1.935929	19359
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	18.601306	86.000002	860000	47.382653	473827
Other Plastics and Rubber	Carbon Black	1333-86-4	0.064888	0.299999	3000	0.165288	1653
Thermoplastics	Epoxy	85954-11-6	2.963231	13.699999	137000	7.548166	75482
Sub-Total			21.629425	100	1000000	55.096106	550961
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.443852	100	1000000	1.130613	11306
Sub-Total			0.443852	100	1000000	1.130613	11306
Total			39.257629			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
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Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/econfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.